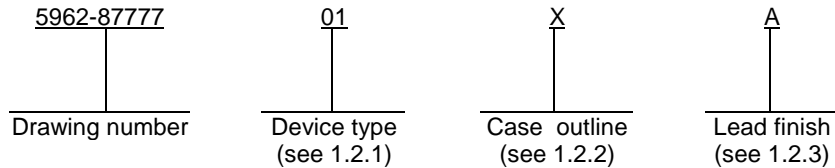


REVISIONS																			
LTR	DESCRIPTION										DATE (YR-MO-DA)				APPROVED				
A	Change for 1.3 collector-emitter voltage maximum limit. Change limits and conditions for base offset voltage, change in emitter-base offset, collector leakage, base leakage, current gain and gain match tests.										89-08-25				M. A. Frye				
B	Drawing updated to reflect current requirements. Editorial changes throughout. - drw										01-01-16				Raymond Monnin				
<p>The original first page of this drawing has been replaced.</p>																			
REV																			
SHEET																			
REV																			
SHEET																			
REV STATUS					REV		B	B	B	B	B	B	B	B	B				
OF SHEETS					SHEET		1	2	3	4	5	6	7	8	9				
PMIC N/A					PREPARED BY					DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216 http://www.dsccl.dla.mil									
STANDARD MICROCIRCUIT DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A					CHECKED BY														
					APPROVED BY														
					DRAWING APPROVAL DATE														
					87-12-11					MICROCIRCUIT, LINEAR, TRANSISTOR ARRAYS/MATCHED PAIR, MONOLITHIC SILICON									
					REVISION LEVEL														
					B					A		67268							
										SHEET									
										1 OF 9									

1. SCOPE

1.1 Scope. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.

1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 Device type. The device type identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	LM194	Transistor supermatch pair

1.2.2 Case outline. The case outline is as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
X	See figure 2	6	Similar to a TO-99 can

1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

1.3 Absolute maximum ratings.

Collector current	20 mA
Collector-emitter voltage.....	35 V dc
Base-emitter current	±10 mA
Maximum power dissipation (P _D)	500 mW
Lead temperature (soldering, 60 seconds).....	+300°C
Storage temperature range.....	-65°C to +150°C
Thermal resistance, junction-to-case (θ _{JC}).....	70°C/W
Thermal resistance, junction-to-case (θ _{JA}).....	230°C/W

1.4 Recommended operating conditions.

Ambient operating temperature range (T _A)	-55°C to +125°C
---	-----------------

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	SIZE A		5962-87777
		REVISION LEVEL B	SHEET 2

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.

3.2.1 Case outline. The case outline shall be in accordance with 1.2.2 herein and figure 2.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	SIZE A		5962-87777
		REVISION LEVEL B	SHEET 3

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Emitter: Base offset voltage	V_{BEO}	$V_{\text{CB}} = 0 \text{ V}, I_{\text{C}} = 1 \text{ mA}$	1	All		± 100	μV
		$V_{\text{CB}} = 35 \text{ V}, I_{\text{C}} = 1 \text{ mA}$	1	All		± 100	
			2, 3			± 350	
		$V_{\text{CB}} = 0 \text{ V}, I_{\text{C}} = 0.3 \text{ mA}$	1	All		± 100	
		$V_{\text{CB}} = 0 \text{ V}, I_{\text{C}} = 100 \mu\text{A}$	1	All		± 100	
		$V_{\text{CB}} = 35 \text{ V}, I_{\text{C}} = 100 \mu\text{A}$	1	All		± 100	
			2, 3			± 350	
		$V_{\text{CB}} = 0 \text{ V}, I_{\text{C}} = 10 \mu\text{A}$	1	All		± 100	
		$V_{\text{CB}} = 35 \text{ V}, I_{\text{C}} = 10 \mu\text{A}$	1	All		± 100	
		$V_{\text{CB}} = 0 \text{ V}, I_{\text{C}} = 1 \mu\text{A}$	1	All		± 100	
		$V_{\text{CB}} = 35 \text{ V}, I_{\text{C}} = 1 \mu\text{A}$	1	All		± 100	
Change in emitter-base offset	ΔV_{BEO}	$V_{\text{CB}} = 0 \text{ to } 35 \text{ V}, I_{\text{C}} = 1 \text{ mA}$	1	All		± 25	μV
		$V_{\text{CB}} = 0 \text{ to } 35 \text{ V}, I_{\text{C}} = 100 \mu\text{A}$	1	All		± 25	
		$V_{\text{CB}} = 0 \text{ to } 35 \text{ V}, I_{\text{C}} = 10 \mu\text{A}$	1	All		± 25	
		$V_{\text{CB}} = 0 \text{ to } 35 \text{ V}, I_{\text{C}} = 1 \mu\text{A}$	1	All		± 25	
		$V_{\text{CB}} = 0 \text{ V}, I_{\text{C}} = 1 \text{ to } 300 \mu\text{A}$	1	All		± 25	
Collector: Collector leakage	I_{CCX}	$V_{\text{CB}} = 35 \text{ V}, \text{COLL } 1 \text{ to COLL } 2$	1	All		± 2	nA
		$V_{\text{CB}} = 35 \text{ V}, \text{COLL } 2 \text{ to COLL } 1$	1	All		± 2	
Collector: Base leakage	I_{CBX}	$V_{\text{CB}} = 35 \text{ V}, \text{COLL } 1 \text{ to BASE } 1$	1	All		± 0.25	nA
		$V_{\text{CB}} = 35 \text{ V}, \text{COLL } 2 \text{ to BASE } 2$	1	All		± 0.25	

**STANDARD
MICROCIRCUIT DRAWING**
DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216-5000

SIZE
A

REVISION LEVEL
B

5962-87777

SHEET
4

TABLE I. Electrical performance characteristics - continued.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Current gain	h_{FE}	$V_{CB} = 0\text{ V}, I_C = 1\text{ mA}$	1	All	350		
		$V_{CB} = 35\text{ V}, I_C = 1\text{ mA}$	1	All	350		
			2, 3		250		
		$V_{CB} = 0\text{ V}, I_C = 100\text{ }\mu\text{A}$	1	All	350		
		$V_{CB} = 35\text{ V}, I_C = 100\text{ }\mu\text{A}$	1	All	350		
		$V_{CB} = 0\text{ V}, I_C = 10\text{ }\mu\text{A}$	1	All	300		
		$V_{CB} = 35\text{ V}, I_C = 10\text{ }\mu\text{A}$	1	All	300		
		$V_{CB} = 0\text{ V}, I_C = 1\text{ }\mu\text{A}$	1	All	200		
		$V_{CB} = 35\text{ V}, I_C = 1\text{ }\mu\text{A}$	1	All	200		
Gain match	h_{FE} match	$V_{CB} = 0\text{ V}, I_C = 1\text{ mA}$	4	All		± 2	%
		$V_{CB} = 35\text{ V}, I_C = 1\text{ mA}$	4	All		± 2	
			5, 6			± 6	
		$V_{CB} = 0\text{ V}, I_C = 100\text{ }\mu\text{A}$	4	All		± 2	
		$V_{CB} = 35\text{ V}, I_C = 100\text{ }\mu\text{A}$	4	All		± 2	
		$V_{CB} = 0\text{ V}, I_C = 10\text{ }\mu\text{A}$	4	All		± 2	
		$V_{CB} = 35\text{ V}, I_C = 10\text{ }\mu\text{A}$	4	All		± 2	

**STANDARD
MICROCIRCUIT DRAWING**
DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216-5000

SIZE
A

5962-87777

REVISION LEVEL
B

SHEET
5

3.5 Marking. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.

3.5.1 Certification/compliance mark. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

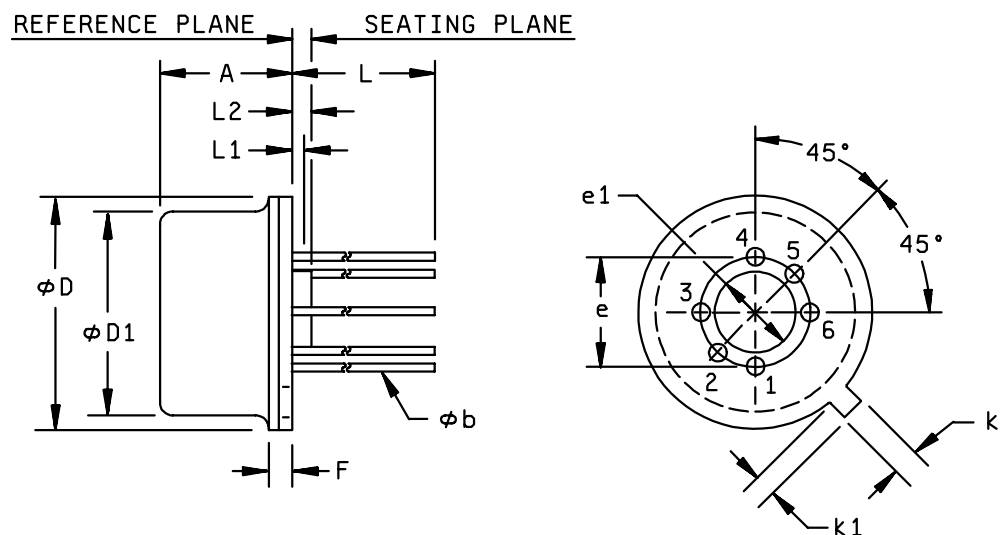
3.8 Notification of change. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.

3.9 Verification and review. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

Device type	01
Case outline	X
Terminal number	Terminal symbol
1	Collector
2	Base
3	Emitter
4	Emitter
5	Base
6	Collector

FIGURE 1. Terminal connections.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	SIZE A		5962-87777
		REVISION LEVEL B	SHEET 6



Symbol	Inches		Millimeters	
	Min	Max	Min	Max
A	0.165	0.185	4.191	4.699
ϕb	0.015	0.016	0.381	0.406
ϕD	0.350	0.370	8.890	9.398
$\phi D1$	0.315	0.335	8.001	8.509
e	0.195	0.205	4.953	5.207
e1	0.120	0.140	3.048	3.556
F		0.035		0.889
k	0.028	0.034	0.711	0.864
k1	0.029	0.045	0.737	1.143
L	0.500		12.700	
L1		0.025		0.635
L2	0.015	0.040	0.318	1.016

FIGURE 2. Case outline X.

**STANDARD
MICROCIRCUIT DRAWING**
DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216-5000

SIZE
A

5962-87777

REVISION LEVEL
B

SHEET
7

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*, 2, 3, 4, 5, 6
Group A test requirements (method 5005)	1, 2, 3, 4, 5, 6
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	SIZE A		5962-87777
		REVISION LEVEL B	SHEET 8

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0674.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	SIZE A		5962-87777
		REVISION LEVEL B	SHEET 9

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 01-01-16

Approved sources of supply for SMD 5962-87777 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8777701XA	27014	LM194H/883

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE
number

27014

Vendor name
and address

National Semiconductor
2900 Semiconductor Dr
PO Box 58090
Santa Clara, CA 95052-8090

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.